

## LEADERSHIP IN ALL MATERIALS FOR ADVANCED PACKAGING

The joined forces of **Alpha Assembly** and **MacDermid Enthone** are working together to help you succeed.

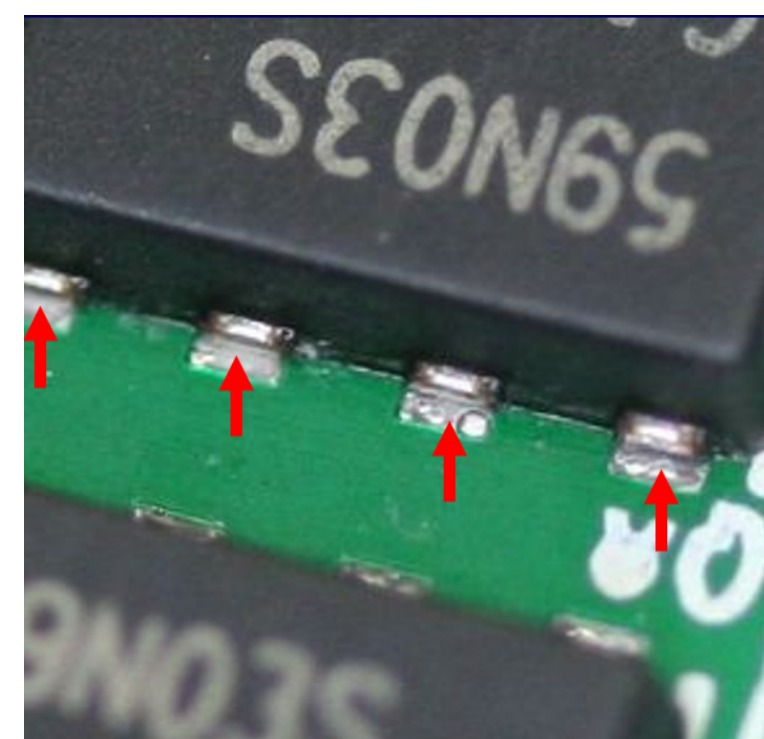
### PackageBond

Adhesion promotion for lead frame packaging which prevents MSL-1 "popcorning".



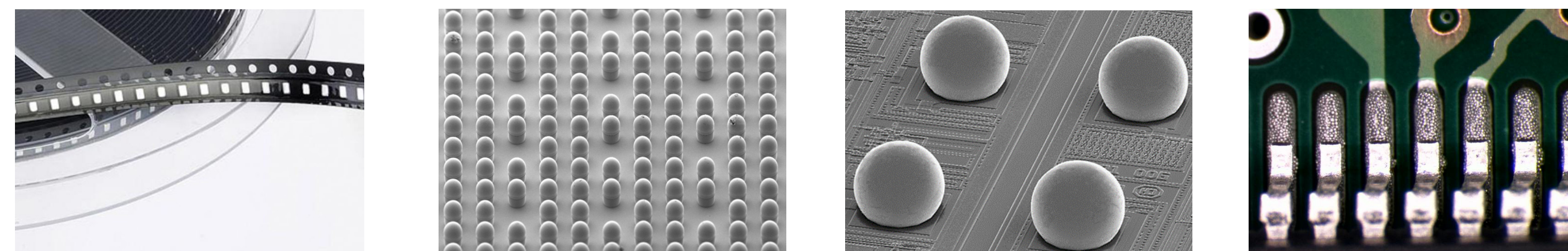
### PackagePrep

An easily soldered metal plating on copper flanks, which allows AOI and joint reliability.



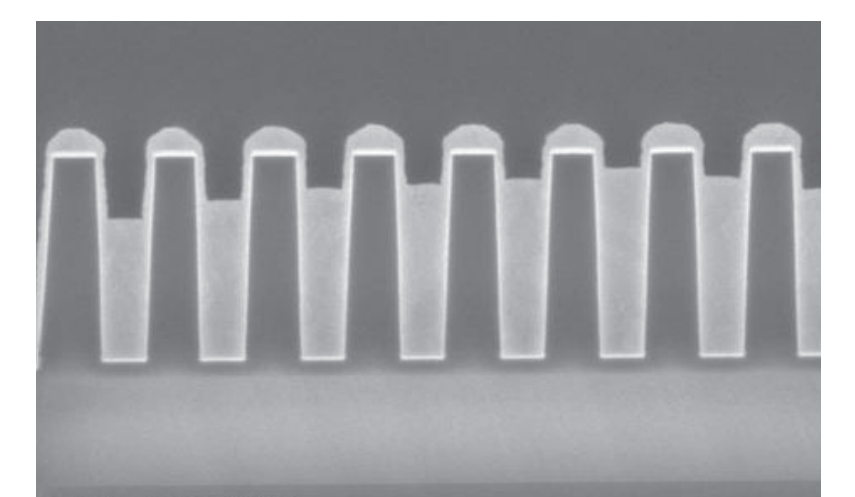
### Assembly Solutions and Advanced Materials

Full set of interconnection materials for semiconductor level, package level and board level assembly.



### Via Form

Copper damascene trusted by leading semi fabs, provides superior filling at the smallest nodes.



### MICROFAB

Full suite of plating for wafer level packaging

- Cu pillar/post
- Redistribution layer (RDL)
- Ni, Sn, Au Bump
- Through silicon via



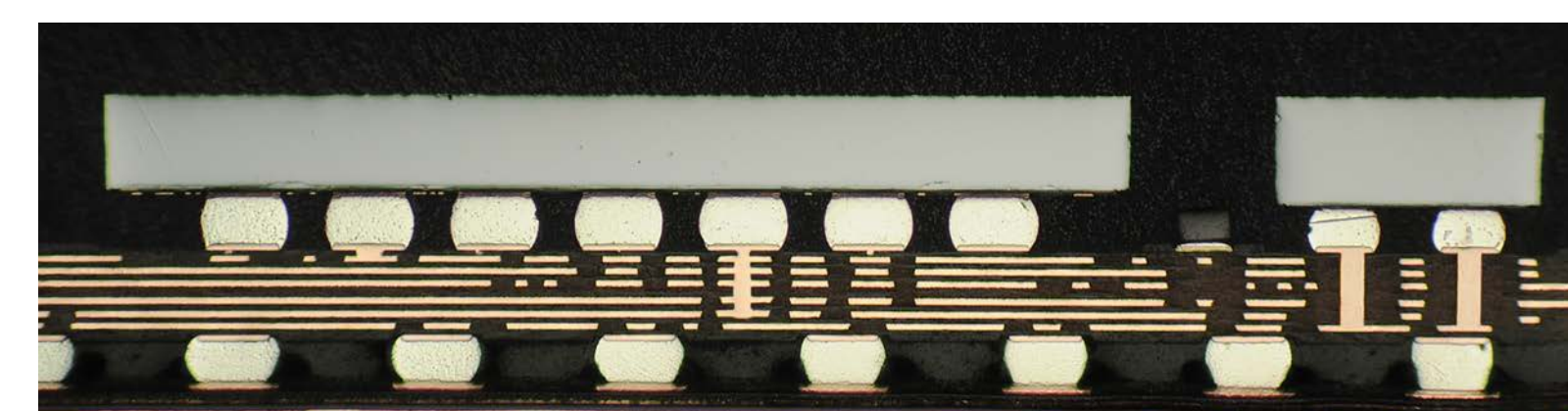
### MacuSpec VF Series

Fills vias while simultaneously plating through holes. Best in industry throwing power and board reliability.



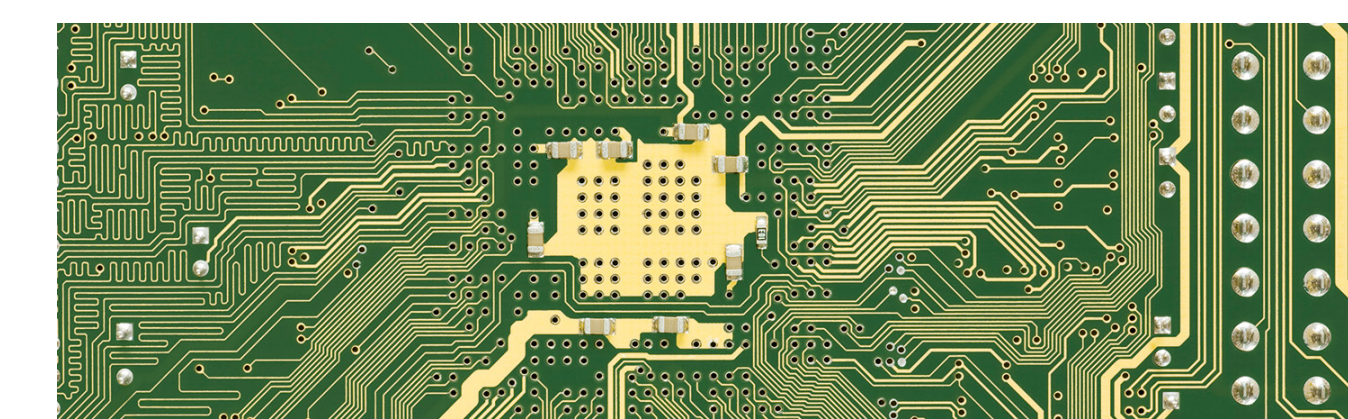
### MSAP

Innovative buildup process for fine line substrates. Comprehensive, optimized selections from copper reduction to final finish.



### Affinity ENIG/ENEPIG 2.0

A revolution in nickel gold control and stability, offering quantifiable gold savings. Reduces gold costs up to 30%.



### Systek THF

Copper filled through holes for the highest electrical, thermal and physical performance. Cooler packages, denser circuitry.

